



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ160N10NS3 G		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA000615148						
<b>Package</b>		PG-TSDSON-8-2		<b>Weight*</b>		40.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	4.56	4.56	45635	45635
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		52	
	non noble metal	zinc	7440-66-6	0.008	0.02		208	
	non noble metal	iron	7439-89-6	0.168	0.42		4170	
wire	non noble metal	copper	7440-50-8	6.808	16.93	17.38	169315	173745
	non noble metal	copper	7440-50-8	0.041	0.10	0.10	1027	1027
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.09		909
	plastics	epoxy resin	-	1.882	4.68		46815	
	inorganic material	silicondioxide	60676-86-0	16.356	40.70	45.47	406792	454516
leadfinish	non noble metal	tin	7440-31-5	0.387	0.96	0.96	9629	9629
plating	noble metal	silver	7440-22-4	0.963	2.39	2.39	23940	23940
solder	non noble metal	tin	7440-31-5	0.037	0.09		915	
	noble metal	silver	7440-22-4	0.046	0.11		1144	
	non noble metal	lead	7439-92-1	1.758	4.37	4.57	43714	45773
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		107	
	non noble metal	iron	7439-89-6	0.086	0.21		2145	
heat sink CLIP	non noble metal	copper	7440-50-8	3.501	8.71	8.93	87078	89357
	inorganic material	phosphorus	7723-14-0	0.002	0.00		47	
	non noble metal	zinc	7440-66-6	0.008	0.02		188	
	non noble metal	iron	7439-89-6	0.151	0.38		3753	
	non noble metal	copper	7440-50-8	6.127	15.24	15.64	152390	156378
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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